

?D%-\$!DC K 9 F H<MF=GHC F

'&\$!'*\$ J8FA

<=: < DC K 9 F H<MF=GHC F : CF D<5G9 7CBHFC@ 5DD@=75H=CBG

:YUhiYg.

" 5` 8]ZigYX GhfiWhifY
" 5ad`]zm]b[;UhY 7cbZ][ifUh]cb
" 6`cW_]b[WUdUV`]hm id hc '*\$\$ jc`hg
" <][\ Xj#Xh 7UdUV`]hm
" DfYggifY 5ggYaV`YX 8Yj]WY

9@97HF=75@ 7<5F57H9F=GH=7G 5B8 F5H=B ; G

6`cW_]b[! CZZ GhUhY

Device Tyy

; Uh]b [

DUFU a YhYf	Gma Vc`	A]b"	AUI"	Hmd"	I b]hg	7 cbX]h]cbg
Peak gate power dissipation	P _{GM}		20		W	
Average gate power dissipation	P _{G(AV)}		4		W	
Gate-trigger current	I _{GT}		200		mA	V _D = 12 V; R _L = 3 ohms; T _j = +25 °C
Gate- trigger voltage	V _{GT}	0.7	3.0		V	V _D = 12 V; R _L = 3 ohms; T _j = +25 °C
Peak negative voltage	V _{GRM}		5		V	

8mbU a]W

DUFU a YhYf	Gma Vc`	A]b"	AUI"	Hmd"	I b]hg	7 cbX]h]cbg
Delay time	t _d		3.0	2.5	s	I _{TM} =100A; V _D =67%V _{DRM} Gate pulse:V _G =30V; R _G =10ohms; t _r =0.1 s; t _p =20 s
Turn-off time (with V _R = -5 V)	t _q			600	s	I _{TM} =2000A; di/dt =-10A/ s; V _R =100V; dv/dt=30V/ s ; V _D =67%V _{DRM} ; T _j =125
Reverse recovery charge	Q _{rr}				C	I _{TM} =2000A di/dt=-10A/ s; V _R =100V; T _j =125

H<9FA5@ 5B8 A97<5B=75@ 7<5F57H9F=GH=7G 5B8 F5H=B ; G

DUFU a YhYf	Gma Vc`	A]b"	AUI"	Hmd"	I b]hg	7 cbX]h]cbg
Operating temperature	T _j	-40	+125		°C	
Storage temperature	T _{stg}	-40	+140		°C	
Thermal resistance - junction to case	R _(j-c)		0.0125		°C/W	Double sided cooled
Thermal resistance - case to heatsink	R _(c-s)		0.004		°C/W	Double sided cooled
Mounting force	F	31	35	33	kN	
Weight	m			0.85	kg	

* Mounting surfaces smooth, flat and greased

